

**METHODS OF FORMING INTEGRATED CIRCUIT DEVICES
INCLUDING INSULATION LAYERS**

ABSTRACT

5 Methods of forming an electronic device including a substrate and a
raised pattern on the substrate are provided. For example, a first insulating
layer may be formed on the raised pattern and on the substrate. More
particularly, forming the first insulating layer may include forming a first
portion of the first insulating layer using a first processing condition and
10 forming a second portion of the first insulating layer using a second
processing condition. After forming the first insulating layer including the
first and second portions, portions of the first insulating layer may be
removed to expose portions of the raised pattern while maintaining portions
of the first insulating layer on the substrate. After removing portions of the
15 first insulating layer, a second insulating layer may be formed on the
exposed portions of the raised pattern and on the maintained portions of
the first insulating layer.